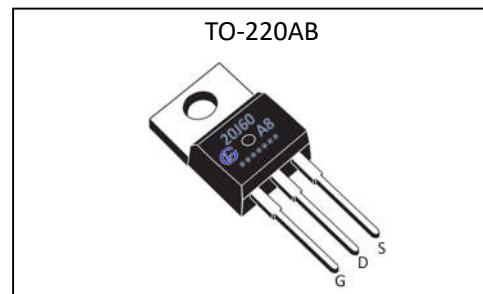


## GL Silicon N-Channel Super-Junction Power MOSFET

### General Description:

GL20J60A8 the silicon N-channel Enhanced VDMOSFETs, is obtained by the self-aligned Superjunction Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-220AB, which accords with the RoHS standard.

$V_{DSS}(T_c=150^\circ\text{C})$	650	V
$V_{DSS}(T_c=25^\circ\text{C})$	600	V
$I_D$	20	A
$P_D(T_c=25^\circ\text{C})$	150	W
$R_{DS(\text{ON})}$	0.12	$\Omega$

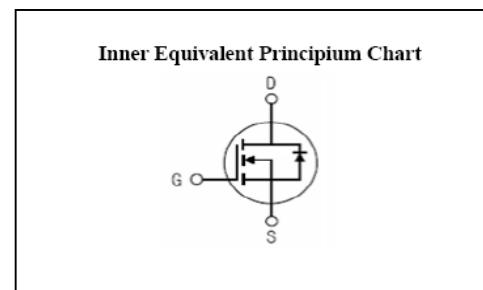


### Features:

- Fast Switching
- Low Gate Charge and  $R_{dson}$
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

### Applications:

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply(UPS)
- Power Factor Correction(PFC)



### Absolute (Tc= 25°C unless otherwise specified) :

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage	600	V
$I_D$	Continuous Drain Current	20	A
	Continuous Drain Current $T_c = 100^\circ\text{C}$	15	A
$I_{DM}^{a1}$	Pulsed Drain Current	60	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
$E_{AS}^{a2}$	Single Pulse Avalanche Energy	532	mJ
$E_{AR}^{a1}$	Avalanche Energy ,Repetitive	166	mJ
$I_{AR}^{a1}$	Avalanche Current	12	A
$dv/dt^{a3}$	Peak Diode Recovery $dv/dt$	15.0	V/ns
$P_D$	Power Dissipation	150	W
	Derating Factor above $25^\circ\text{C}$	1.2	$\text{W}/^\circ\text{C}$
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
$T_L$	MaximumTemperature for Soldering	300	$^\circ\text{C}$



# GL20J60A8

**GL Silicon N-Channel Super-Junction Power MOSFET**

**Electrical Characteristics** (T<sub>c</sub>= 25°C unless otherwise specified):

## OFF Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	600	--	--	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Bvdss Temperature Coefficient	I <sub>D</sub> =250μA, Reference 25°C	--	0.60	--	V/°C
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V, T <sub>a</sub> =25°C	--	--	1	μA
		V <sub>DS</sub> =480V, V <sub>GS</sub> =0V, T <sub>a</sub> =125°C	--	--	250	
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	V <sub>GS</sub> =+30V	--	--	10	μA
I <sub>GSS(R)</sub>	Gate to Source Reverse Leakage	V <sub>GS</sub> =-30V	--	--	-10	μA

## ON Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R <sub>DSON</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	--	0.12	0.15	Ω
V <sub>Gsth</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
Pulse width t <sub>p</sub> ≤380μs, δ≤2%						

## Dynamic Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g <sub>f</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	--	18.8	--	S
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V	--	1600	--	pF
C <sub>oss</sub>	Output Capacitance	f=1.0MHz	--	14	--	
C <sub>rss</sub>	Reverse Transfer Capacitance		--	225	--	

## Resistive Switching Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =300V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>g</sub> =25Ω	--	48	--	ns
t <sub>r</sub>	Rise Time		--	108	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		--	176	--	
t <sub>f</sub>	Fall Time		--	50	--	
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =20A, V <sub>DD</sub> =480V V <sub>GS</sub> =0 to 10V	--	41	--	nC
Q <sub>gs</sub>	Gate to Source Charge		--	8	--	
Q <sub>gd</sub>	Gate to Drain ( "Miller" )Charge		--	15	--	

**Source-Drain Diode Characteristics**

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I <sub>S</sub>	Continuous Source Current (Body Diode)		--	--	20	A
I <sub>SM</sub>	Maximum Pulsed Current (Body Diode)		--	--	60	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	--	0.95	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =20A, T <sub>j</sub> =25°C	--	440	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/us, V <sub>GS</sub> =0V	--	5	--	uC
Pulse width t <sub>p</sub> ≤380μs, δ≤2%						

Symbol	Parameter	Typ.	Units
R <sub>θJC</sub>	Junction-to-Case	0.83	°C/W
R <sub>θJA</sub>	Junction-to-Ambient	62.5	°C/W

<sup>a1</sup>: Repetitive rating; pulse width limited by maximum junction temperature

<sup>a2</sup>: I<sub>AS</sub>= 6A, V<sub>DD</sub>= 50V, R<sub>G</sub>= 25Ω, Starting T<sub>j</sub>= 25°C

<sup>a3</sup>: I<sub>SD</sub>=20A,di/dt≤100A/us,V<sub>DD</sub>≤BV<sub>DS</sub>, Start T<sub>j</sub>=25°C

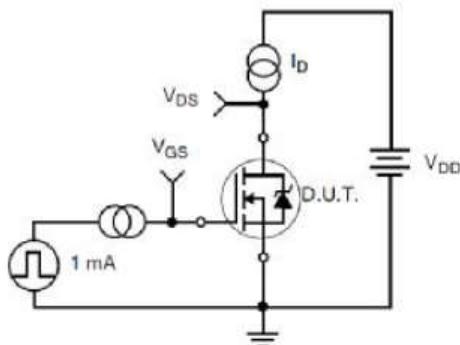
**Test Circuit and Waveform**


Figure 17. Gate Charge Test Circuit

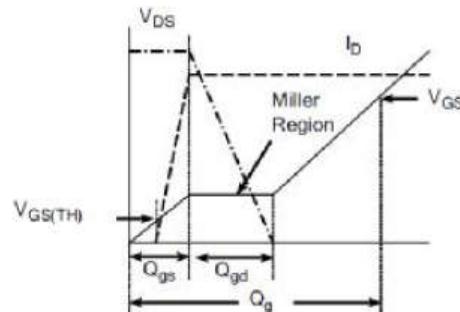


Figure 18. Gate Charge Waveform

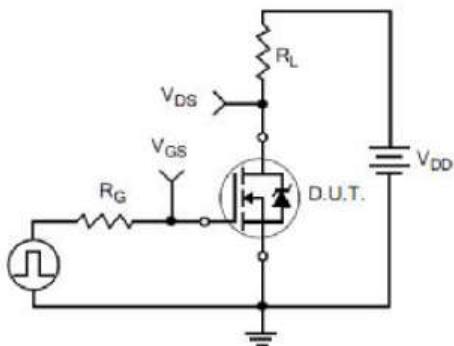


Figure 19. Resistive Switching Test Circuit

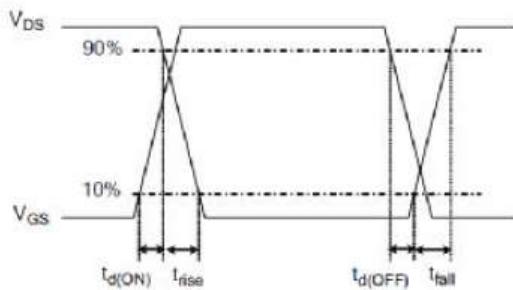
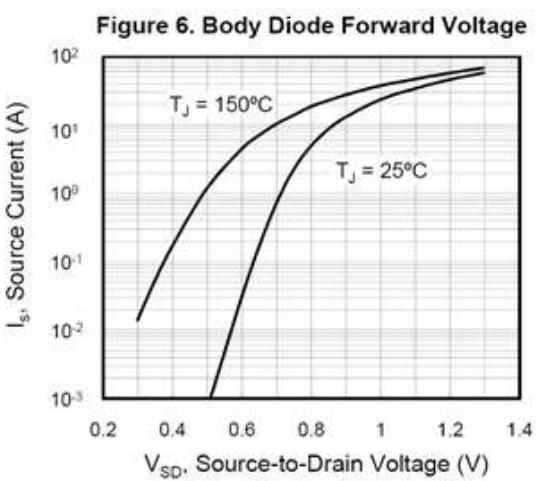
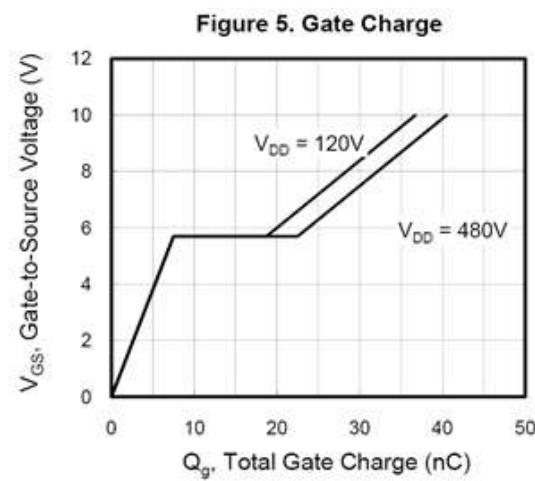
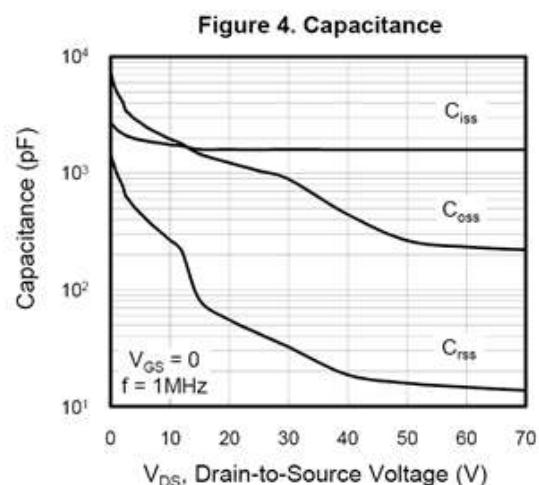
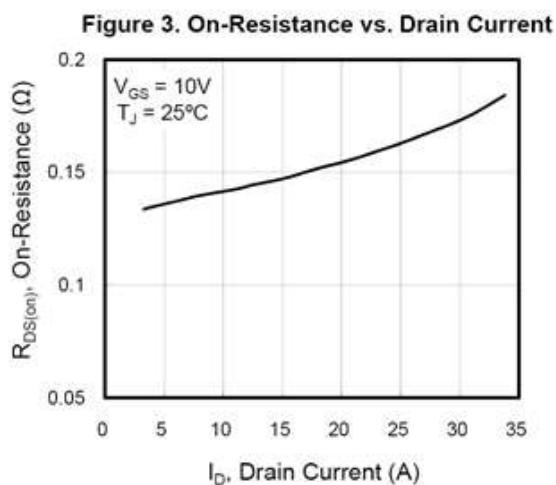
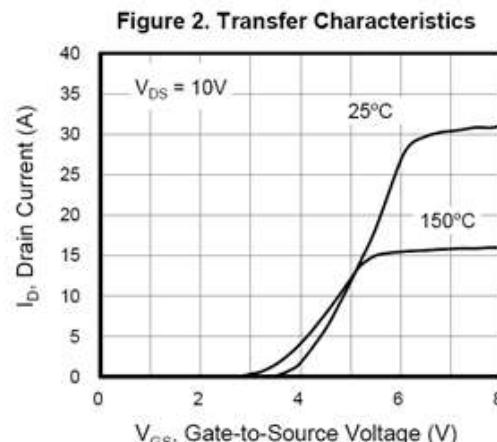
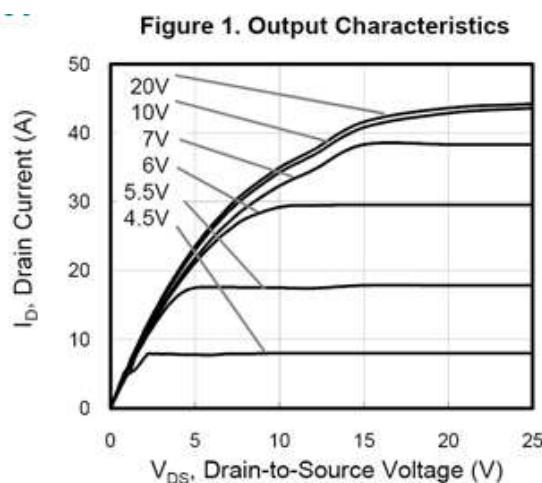
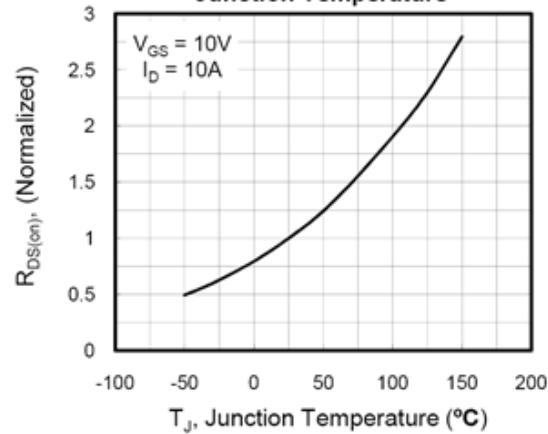


Figure 20. Resistive Switching Waveforms

**Typical Characteristics**


## GL Silicon N-Channel Super-Junction Power MOSFET

Figure 7. On-Resistance vs.  
Junction TemperatureFigure 8. Threshold Voltage vs.  
Junction Temperature